

WCM2001

N- and P-Channel Complementary, 20V, Power MOSFET

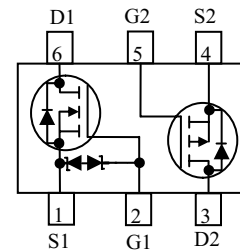
<http://www.omnivision-group.com/>

V_{DS} (V)	Max. $R_{DS(on)}$ (m Ω)
N-Channel 20	500@ $V_{GS}=4.5V$
	835@ $V_{GS}=2.5V$
ESD Rating:2000V HBM	
P-Channel -20	106@ $V_{GS}=-4.5V$
	155@ $V_{GS}=-2.5V$



Descriptions

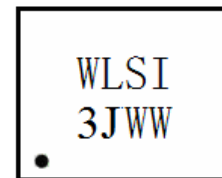
The WCM2001 is the N-Channel and P-Channel enhancement MOS Field Effect Transistor as a single package for DC-DC converter or level shift applications, uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. Standard Product WCM2001 is Pb-free and Halogen-free.



Pin configuration (Top view)

Features

- Trench Technology
- Supper high density cell design
- Excellent ON resistance
- Extremely Low Threshold Voltage
- Package DFN2x2-6L



WLSI = Company Code

3J = Device Code

WW = Week Code

Marking

Applications

- Driver: Relays, Solenoids, Lamps, Hammers
- Power supply converters circuit
- Load/Power Switching for portable device

Order information

Device	Package	Shipping
WCM2001-6/TR	DFN2x2-6L	3000/Tape&Reel

Absolute Maximum ratings

Parameter		Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage		V _{DS}	20	-20	V
Gate-Source Voltage		V _{GS}	±10	±8	
Continuous Drain Current	T _A =25°C	I _D	1.2	-3.6	A
	T _A =70°C		0.9	-2.9	A
Pulsed Drain Current ^d		I _{DM}	2	-6	A
Power Dissipation ^c	T _A =25°C	P _D	1.1	2.0	W
	T _A =70°C		0.7	1.3	
Operating Junction Temperature		T _J	-55 to 150		°C
Storage Temperature Range		T _{STG}	-55 to 150		°C

Thermal resistance ratings

Single Operation (N-Channel)					
Parameter		Symbol	Typical	Maximum	Unit
Junction-to-Ambient Thermal Resistance ^a	t ≤ 10 s	R _{θJA}	74	113	°C/W
	Steady State		102	122	
Junction-to-Ambient Thermal Resistance ^b	t ≤ 10 s	R _{θJA}	156	188	
	Steady State		223	268	
Single Operation (P-Channel)					
Parameter		Symbol	Typical	Maximum	Unit
Junction-to-Ambient Thermal Resistance ^a	t ≤ 10 s	R _{θJA}	51	61	°C/W
	Steady State		77	92	
Junction-to-Ambient Thermal Resistance ^b	t ≤ 10 s	R _{θJA}	138	165	
	Steady State		199	239	

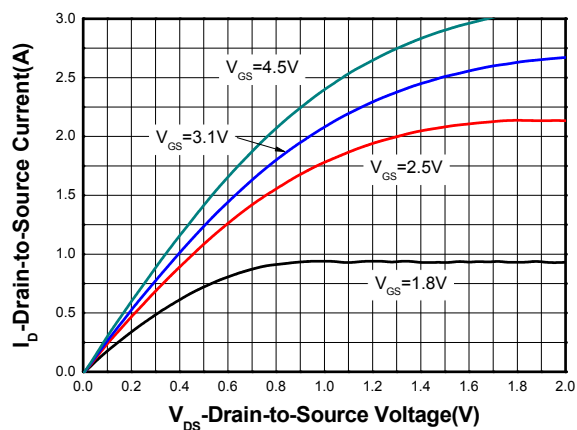
Note:

- FR-4 board (38mm X 38mm X t1.6mm, 70um Copper) partially covered with copper (645mm² area)
- FR-4 board (38mm X 38mm X t1.6mm, 70um Copper) minimum pad covered with copper
- The power dissipation P_D is based on Junction-to-Ambient thermal resistance $R_{\theta JA}$ $t \leq 10\text{s}$ value and the $T_{J(MAX)}=150^{\circ}\text{C}$.
- Repetitive rating, ~10us pulse width, duty cycle ~1%, keep initial $T_J = 25^{\circ}\text{C}$, the maximum allowed junction temperature of 150°C .
- The static characteristics are obtained using ~380us pulses, duty cycle ~1%.

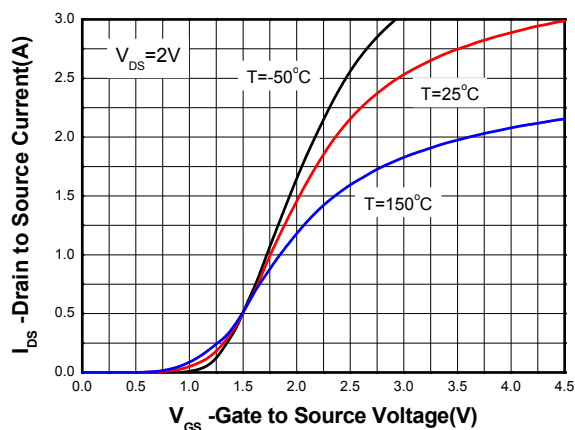
N-Channel Electronics Characteristics (Ta=25°C, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0 V, I _D = 250uA	20			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =16V, V _{GS} = 0V			1	uA
Gate-to-source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±10V			±10	uA
ON CHARACTERISTICS						
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} = V _{DS} , I _D = 250uA	0.45	0.7	1.0	V
Drain-to-source On-resistance	R _{DS(on)}	V _{GS} = 4.5V, I _D =800mA		334	500	mΩ
		V _{GS} = 3.1V, I _D =600mA		377	660	
		V _{GS} = 2.5V, I _D =300mA		417	835	
		V _{GS} = 1.8V, I _D =200mA		553	1380	
CHARGES, CAPACITANCES AND GATE RESISTANCE						
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1.0MHz, V _{DS} = 10 V		29		pF
Output Capacitance	C _{OSS}			11		
Reverse Transfer Capacitance	C _{RSS}			4		
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 4.5 V, V _{DS} = 10 V, I _D =550mA		0.42		nC
Gate-to-Source Charge	Q _{GS}			0.1		
Gate-to-Drain Charge	Q _{GD}			0.16		
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	td _(ON)	V _{GS} = 4.5 V, V _{DS} = 10 V, I _D =550mA, R _G =6Ω		5.9		ns
Rise Time	tr			4.8		
Turn-Off Delay Time	td _(OFF)			15.5		
Fall Time	tf			3.9		
BODY DIODE CHARACTERISTICS						
Forward Voltage	V _{SD}	V _{GS} = 0 V, I _S = 800mA		0.9	1.2	V

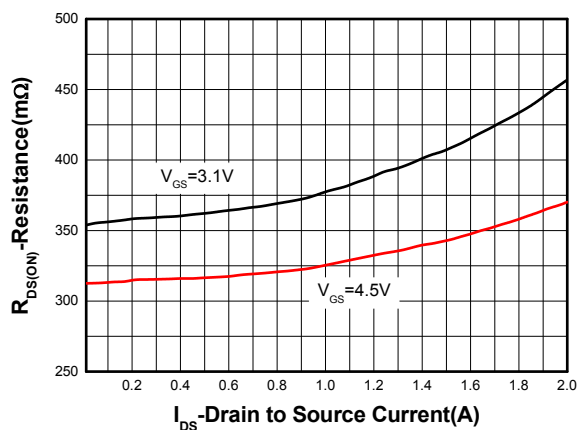
Typical Characteristics (Ta=25°C, unless otherwise noted)



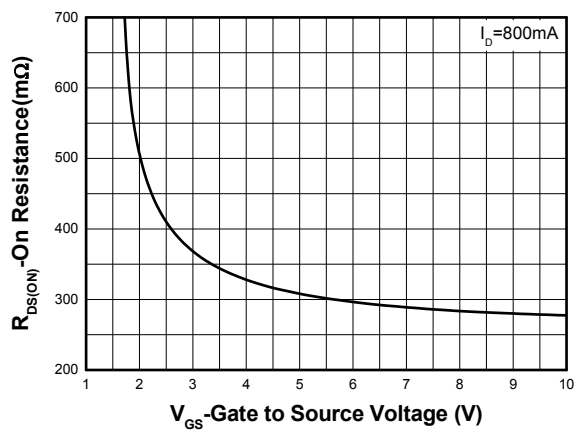
Output Characteristics ^d



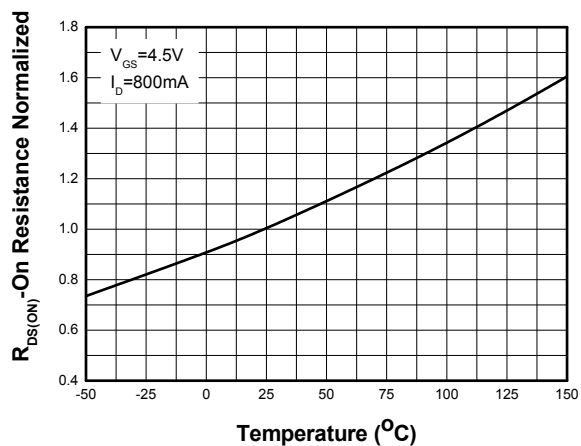
Transfer Characteristics ^d



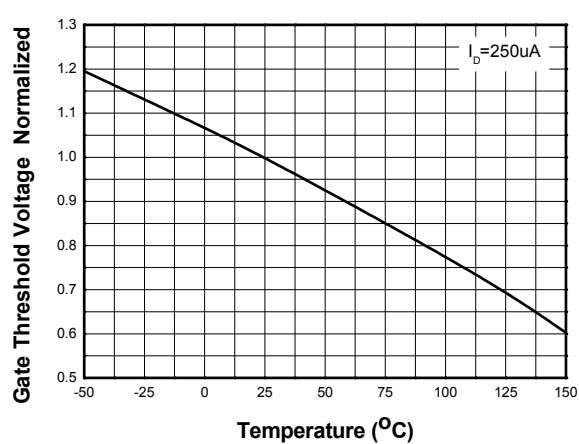
On-Resistance vs. Drain Current ^d



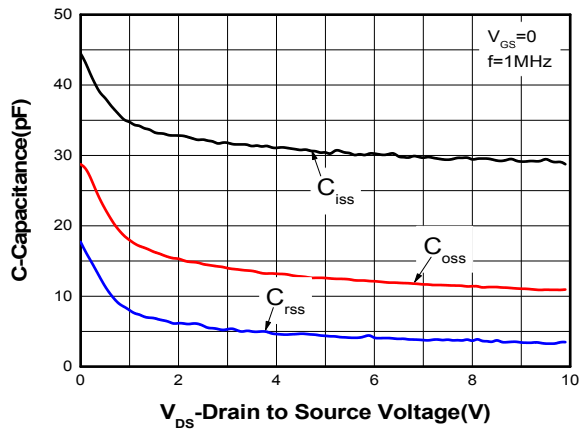
On-Resistance vs. Gate-to-Source Voltage ^d



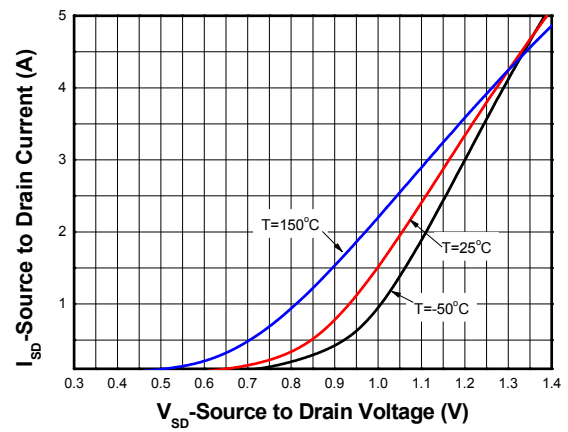
On-Resistance vs. Junction Temperature ^d



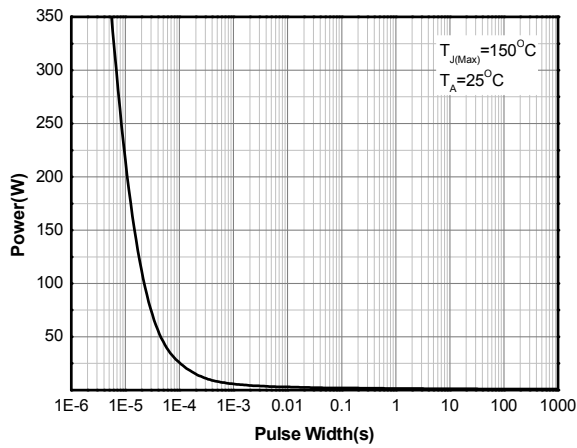
Threshold Voltage vs. Temperature



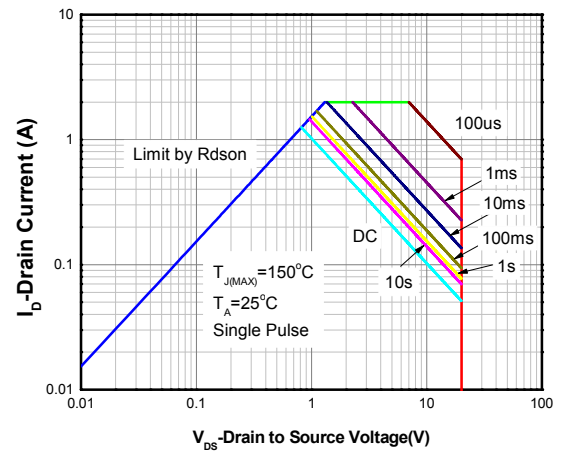
Capacitance



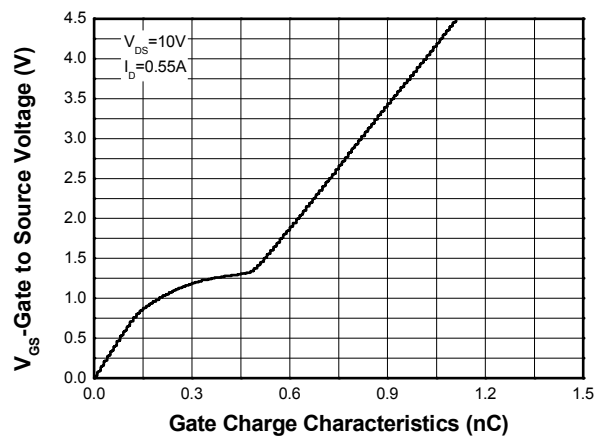
Body Diode Forward Voltage^d



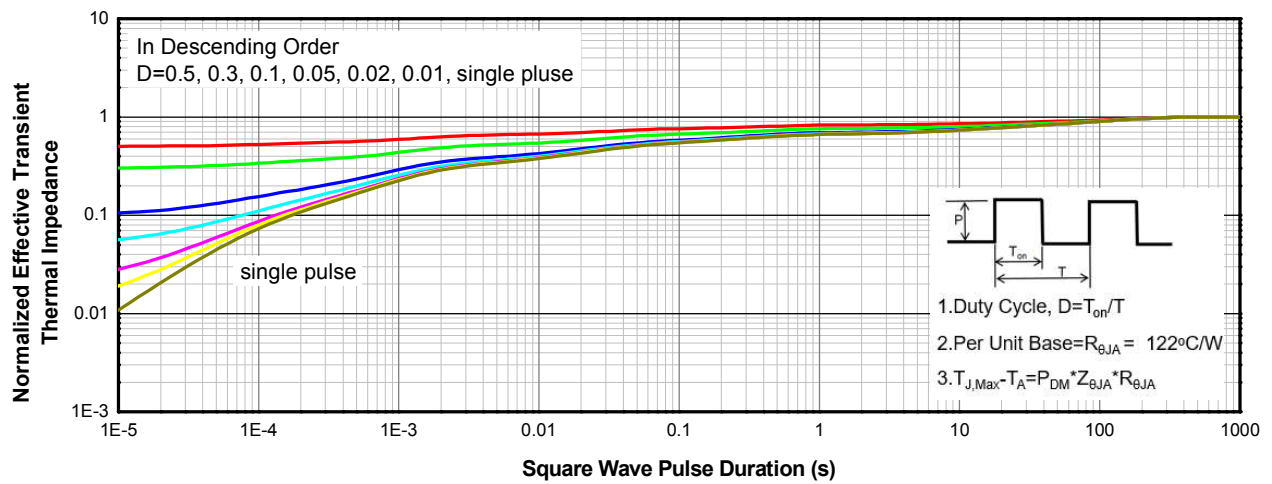
Single Pulse power



Safe Operating Power



Gate Charge Characteristics

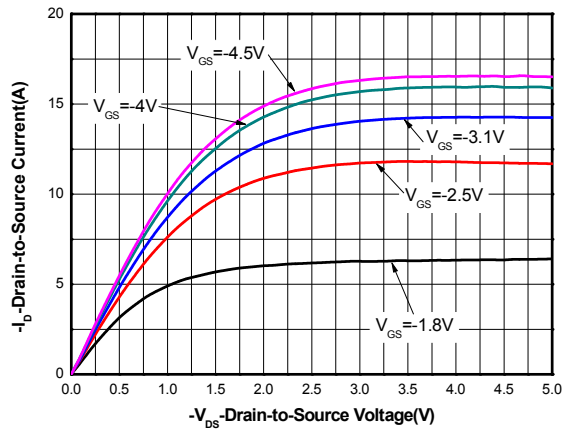


Transient thermal response (Junction-to-Ambient)

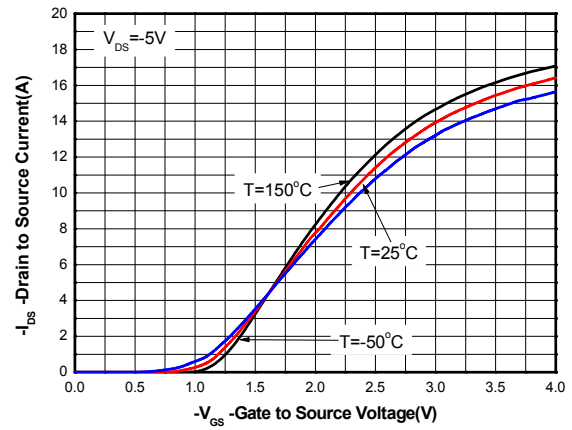
P-Channel Electronics Characteristics (Ta=25°C, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0 V, I _D = -250uA	-20			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-16V, V _{GS} = 0V			-1	uA
Gate-to-source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±8V			±100	nA
ON CHARACTERISTICS						
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} = V _{DS} , I _D = -250uA	-0.45	-0.7	-1	V
Drain-to-source On-resistance	R _{DS(on)}	V _{GS} = -4.5V, I _D = -2.7A		85	106	mΩ
		V _{GS} = -2.5V, I _D = -2.2A		107	155	
CHARGES, CAPACITANCES AND GATE RESISTANCE						
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1.0MHz, V _{DS} = -10V		290		pF
Output Capacitance	C _{OSS}			64		
Reverse Transfer Capacitance	C _{RSS}			48		
Total Gate Charge	Q _{G(TOT)}	V _{GS} =-4.5 V, V _{DS} =-10 V, I _D =-2.3 A		5.9		nC
Threshold Gate Charge	Q _{G(TH)}			0.4		
Gate-to-Source Charge	Q _{GS}			0.8		
Gate-to-Drain Charge	Q _{GD}			1.4		
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	td(ON)	V _{GS} = -4.5 V, V _{DS} =-6 V, I _D =-1A, R _G =6Ω		8.5		ns
Rise Time	tr			11		
Turn-Off Delay Time	td(OFF)			34.6		
Fall Time	tf			10		
BODY DIODE CHARACTERISTICS						
Forward Voltage	V _{SD}	V _{GS} = 0 V, I _S = -1A		-0.85	-1.5	V

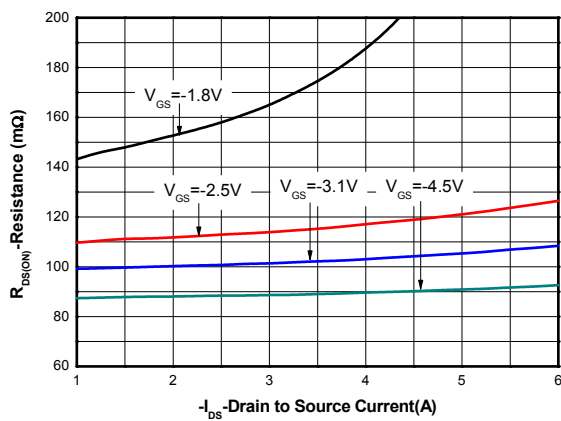
Typical Characteristics (Ta=25°C, unless otherwise noted)



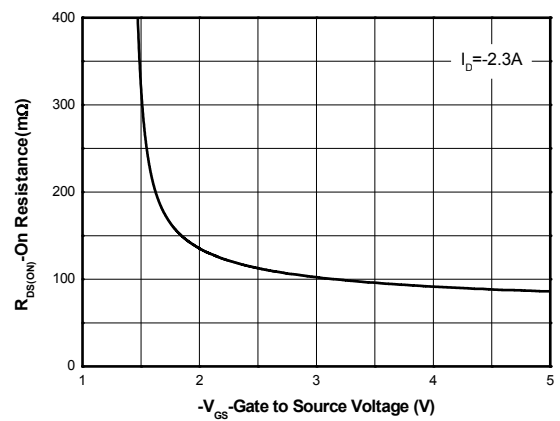
Output Characteristics ^d



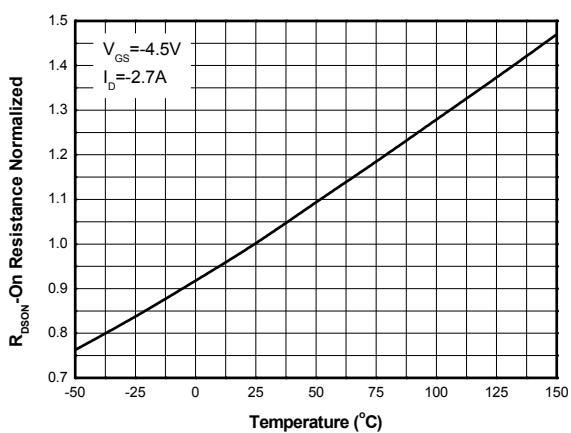
Transfer Characteristics ^d



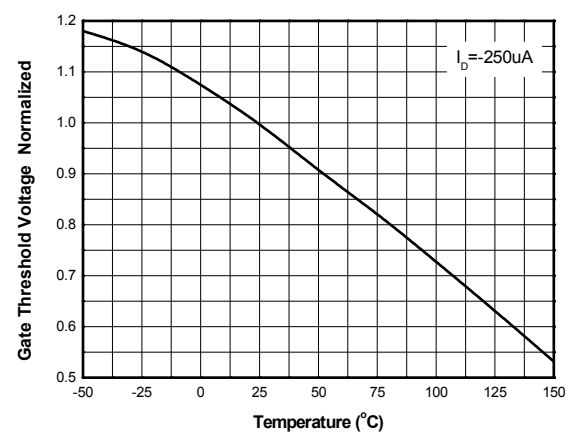
On-Resistance vs. Drain Current ^d



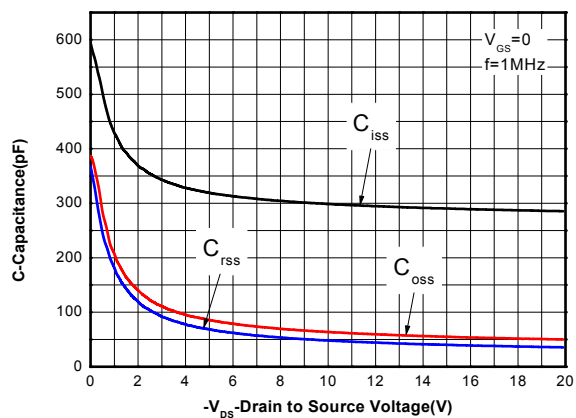
On-Resistance vs. Gate-to-Source Voltage ^d



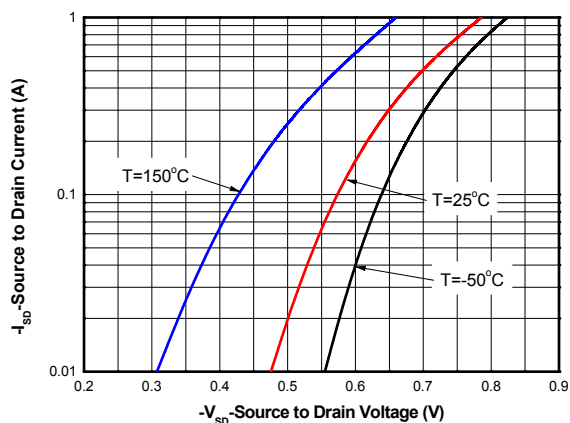
On-Resistance vs. Junction Temperature ^d



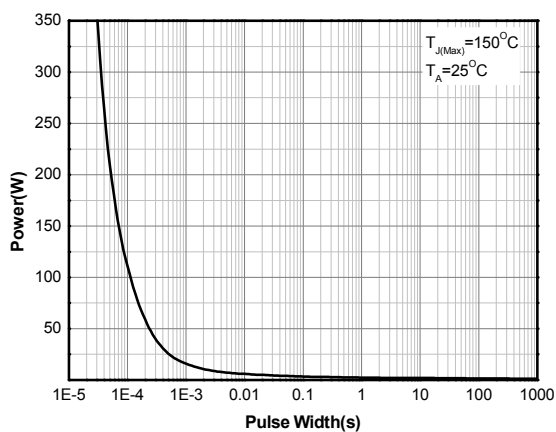
Threshold Voltage vs. Temperature



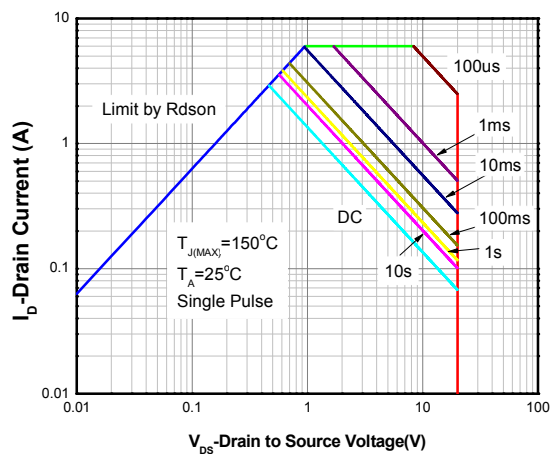
Capacitance



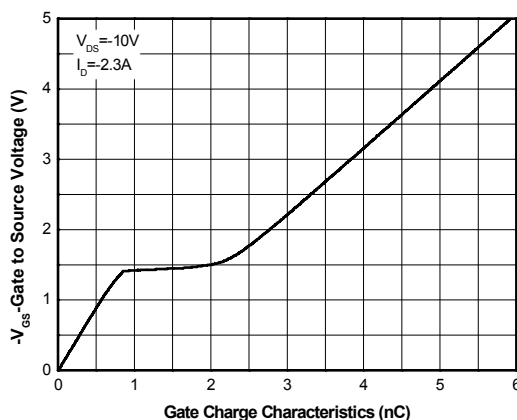
Body Diode Forward Voltage^d



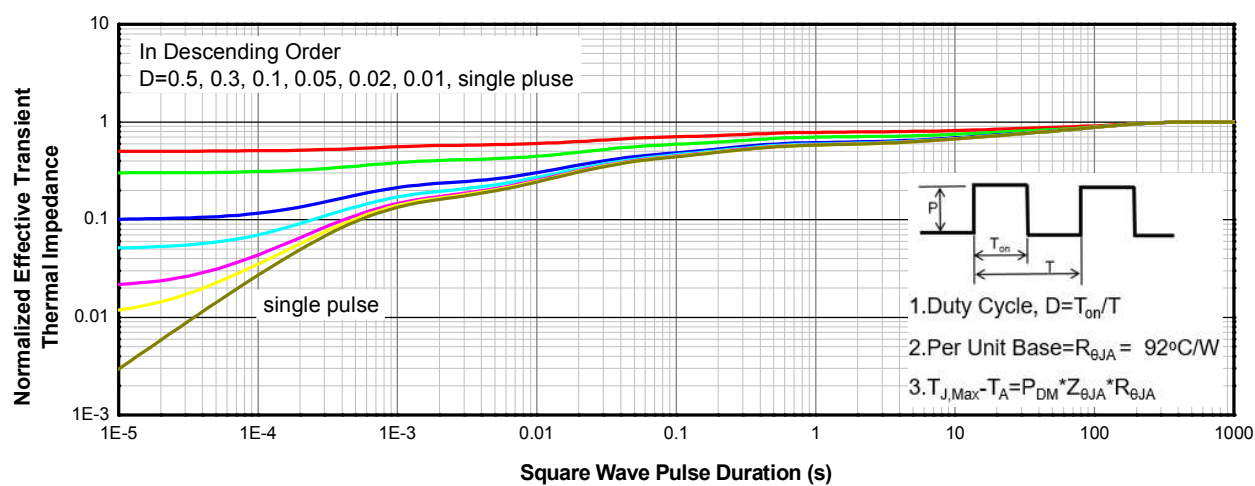
Single Pulse power



Safe Operating Power



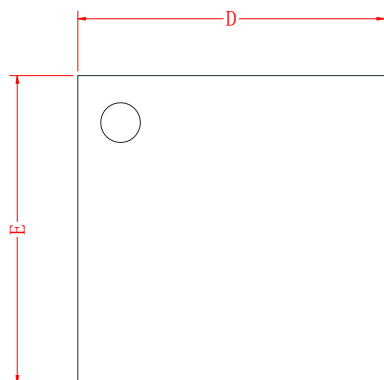
Gate Charge Characteristics



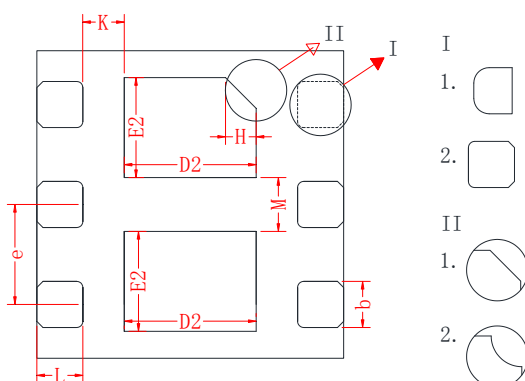
Transient thermal response (Junction-to-Ambient)

PACKAGE OUTLINE DIMENSIONS

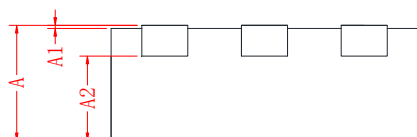
DFN2x2-6L



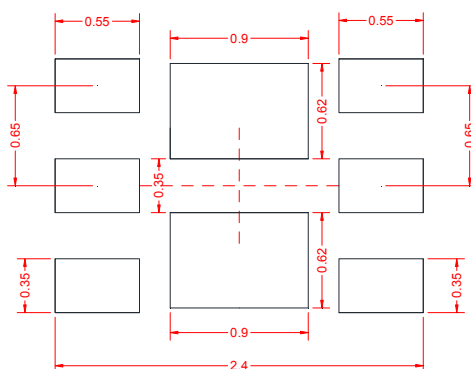
TOP VIEW



BOTTOM VIEW



SIDE VIEW

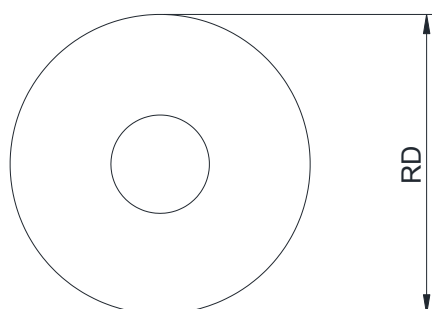


RECOMMENDED LAND PATTERN(Unit:mm)

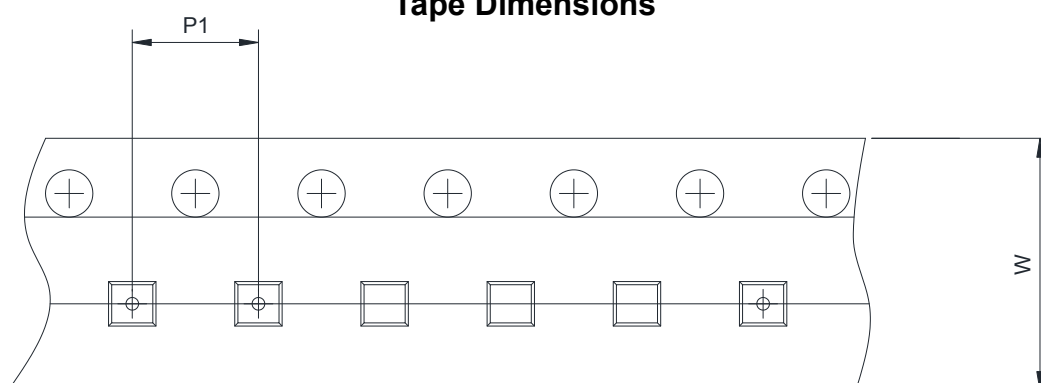
Symbol	Dimensions in Millimeters		
	Min.	Typ.	Max.
A	0.70	0.75	0.80
A1	0.00	-	0.05
A2	0.203 Ref		
D	1.90	2.00	2.10
E	1.90	2.00	2.10
D2	0.76	0.93	1.10
E2	0.44	0.60	0.75
b	0.20	0.28	0.35
L	0.17	0.28	0.38
K	0.17	0.27	0.37
H	0.2 Ref		
M	0.25	0.35	0.45
e	0.65 BSC		

TAPE AND REEL INFORMATION

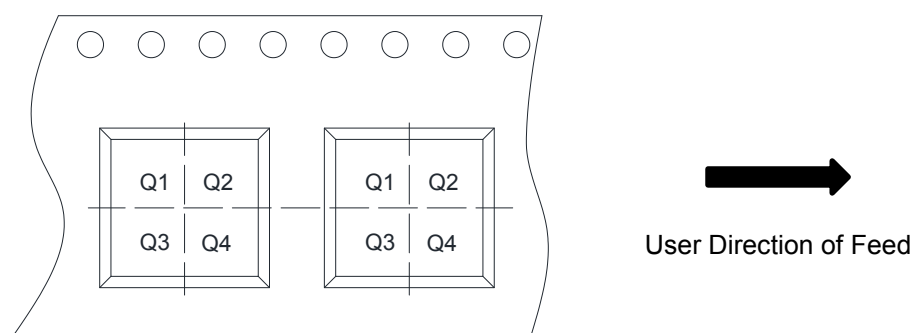
Reel Dimensions



Tape Dimensions



Quadrant Assignments For PIN1 Orientation In Tape



RD	Reel Dimension	☒ 7inch	☐ 13inch
W	Overall width of the carrier tape	☒ 8mm	☐ 12mm ☐ 16mm
P1	Pitch between successive cavity centers	☐ 2mm	☒ 4mm ☐ 8mm
Pin1	Pin1 Quadrant	☒ Q1	☐ Q2 ☐ Q3 ☐ Q4